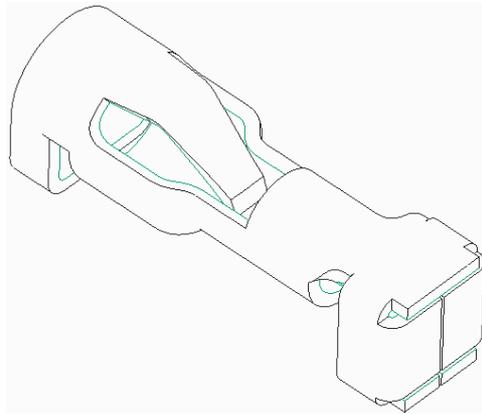


1. INTRODUCTION

This specification covers the requirements for application of Slim WtoB Poke in connector for use on lighting field. When corresponding with TE Connectivity Personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.



Connector

Figure 1

2. REFERENCE MATERIAL

2.1. Revision Summary

Revision B – Update the wire size for 2834010-3.

2.2. Customer Assistance

Reference Product Base Part Numbers 2834010-3&2834012-3 are representative of the poke in connector. Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product information. Such information can be obtained through a local TE Connectivity Representative.

2.3. Drawings

Customer Drawings for specific products are available from the responsible TE Connectivity Engineering department via the service network. The information contained in the Customer Drawings takes priority if there is a conflict with this specification or with any other technical documentation supplied by TE Connectivity.

3. REQUIREMENTS

3.1. Safety:

DO NOT stack product shipping containers so high that the containers buckle or deform.

3.2. Limitations:

The connectors are designed to operate in a temperature range of -40°C to 125°C

3.3. Material

Contact is made of copper alloy;

Under-plated overall with nickel, and plated with tin;

3.4. Storage

A. Ultraviolet Light

Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the connector material.

B. Shelf Life

The contacts and connectors should remain in the shipping containers until ready for use to prevent deformation to components. The components should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

C. Chemical Exposure

DO NOT store the contacts or connectors near any chemical listed below as they may cause stress corrosion cracking in the components.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates

3.5. Wire Selection and Preparation

These connectors will accept 16 to 24 AWG range wire; The applicable wire size and type are list in table 1.

Table 1 RECOMMENDED WIRE

P/N	Wire Size	Wire Type		Insulation Diameter	Strip Length
2834012-3	16 AWG	UL1007-16	Solid	2.30mm	7.0+/-0.3mm
	18 AWG	UL1007-18	Solid		
		UL1007-18(16)	Stranded(Tin-dipped)		
	20 AWG	UL1007-20	Solid		
2834010-3	20 AWG	UL1007-20	Solid	1.55mm	5.5+/-0.3mm
		UL1007-20(7)	Stranded(Tin-dipped)		
	22 AWG	UL1007-22	Solid		
		UL1007-22(7)	Stranded(Tin-dipped)		
		24 AWG	UL1007-24		

The typical unacceptable wire preparation example is shown on Figure 2.

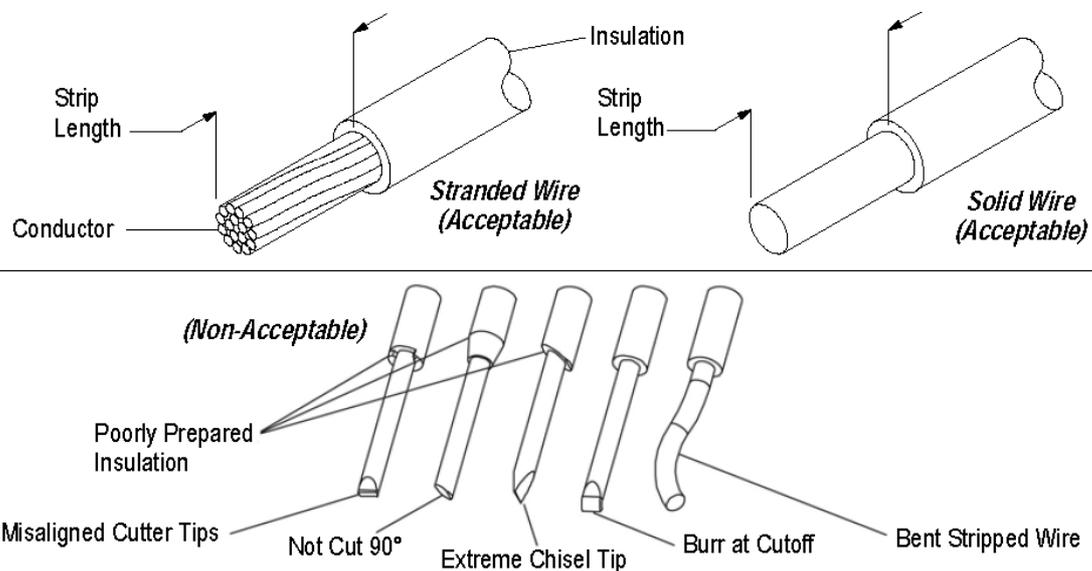


Figure 2

3.6 Assembly Procedure

In the field, these kits must be assembled by a qualified electrician in accordance with national and local electrical codes and the following instructions.



Turn off power before removing or installing connector.

1. Select the proper assembly for your production requirements.
2. Insert each stripped wire into the poke-in slot of the connector until the stripped wire is pushed to the rear stop position. The maximum allowed insertion angle is 5° (Figure 3).

The wire retention side of the connector is for **ONE TIME USE ONLY, DO NOT REMOVE AND REPLACE WIRES.**

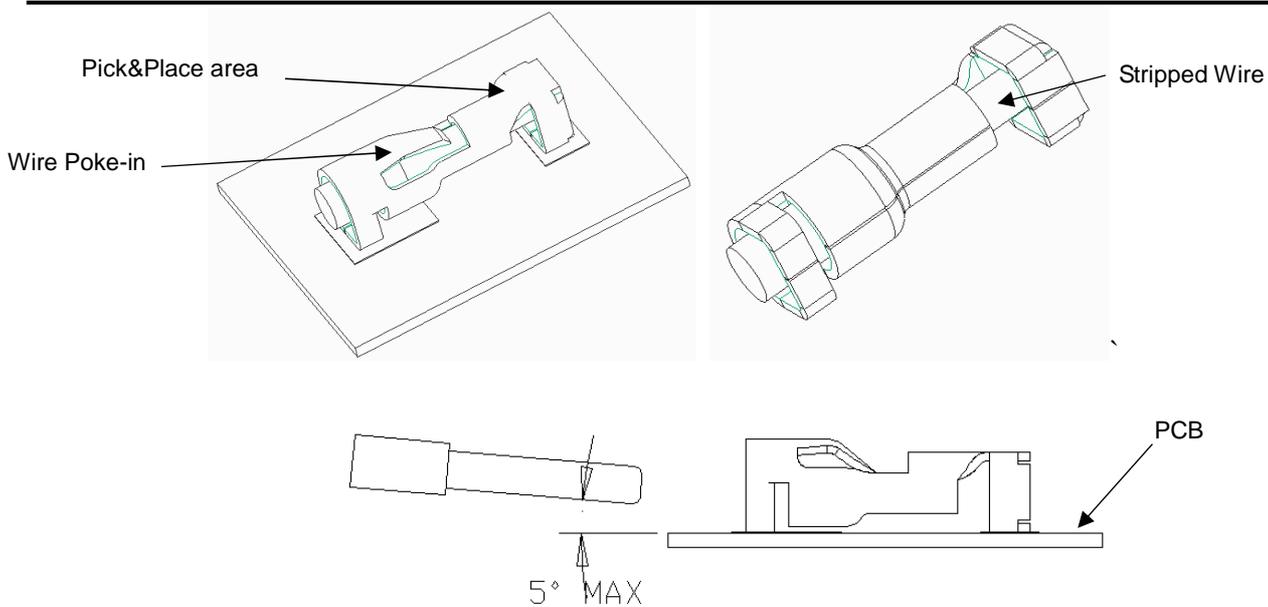


Figure 3

3.7. PC Board

A. Material and Thickness

Common pc board materials may be used such as glass epoxy (FR-4 or G-10), Aluminum-clad pc boards and flex circuits. The pc board thickness may vary to suit the end use thickness.

B. Tolerance

Maximum allowable bow of the pc board shall be 0.10 mm over the length of the connector.

C. Pads

The pc board circuit pads must be solderable in accordance with IPC J-STD-003.

D. Layout

The pc board layout must be designed using the dimensions provided on the customer drawing:

C-2834010&C-2834012 for the specific connector.

The layout should be located on the edge of the PCB for the wire easy inserting.

3.8. Replacement/Repair

The Connector could not be reworked and replaced.

4. QUALIFICATION

Qualification under process by Underwriters Laboratories Inc.

5. SOLDERING

Observe guidelines and procedures when soldering contacts. Solder, clean, and dry all leads to contacts according to the following. The connectors should be soldered using vapor phase reflow (VPR), double-sided, non-focused infrared (IR), forced air convection, or equivalent soldering techniques. All solder joints should conform to the Workmanship Specification IPC-A-610 and IPC J-STD-001.

A. Flux Selection

Contacts must be fluxed prior to soldering with a mildly active, rosin base flux. Selection of the flux will depend on the type of pc board and other components mounted on the board. Additionally, the flux must be compatible with the wave solder line, manufacturing, health, and safety requirements.

B. Connectors with SMT Contacts

1. Solderability

The pc board pads must be solderable in accordance with IPC/EIA J-STD-003 and all other requirements for surface mount contacts specified in this document.

2. Solder Paste Characteristics

- a. Alloy type shall be SAC 305; Sn 96.5/Ag 3.0/Cu 0.5.
- b. Flux incorporated in the paste shall be rosin, mildly active (RMA) type.
- c. Paste will be at least 80% solids by volume.
- d. Mesh designation -200 to +325 (74 to 44 square micron openings, respectively).
- e. Minimum viscosity of screen print shall be 5x10% cp (centipoise).
- f. Minimum viscosity of stencil print shall be 7.5x10% cp (centipoise).

3. Process

Connectors with surface mount contacts should be soldered using vapor phase (VPR), double-sided, non-focused infrared reflow (IR) or equivalent soldering techniques. Due to many variables involved with the reflow process (i.e., component density, orientation, etc.), it is recommended that trial runs be conducted under actual manufacturing conditions to ensure product and process compatibility.

The lead-free reflow profile is shown in Figure 4

Kester Lead-Free Reflow Profile
Alloys: Sn96.5/Ag3.0/Cu0.5 and Sn96.5/Ag3.5

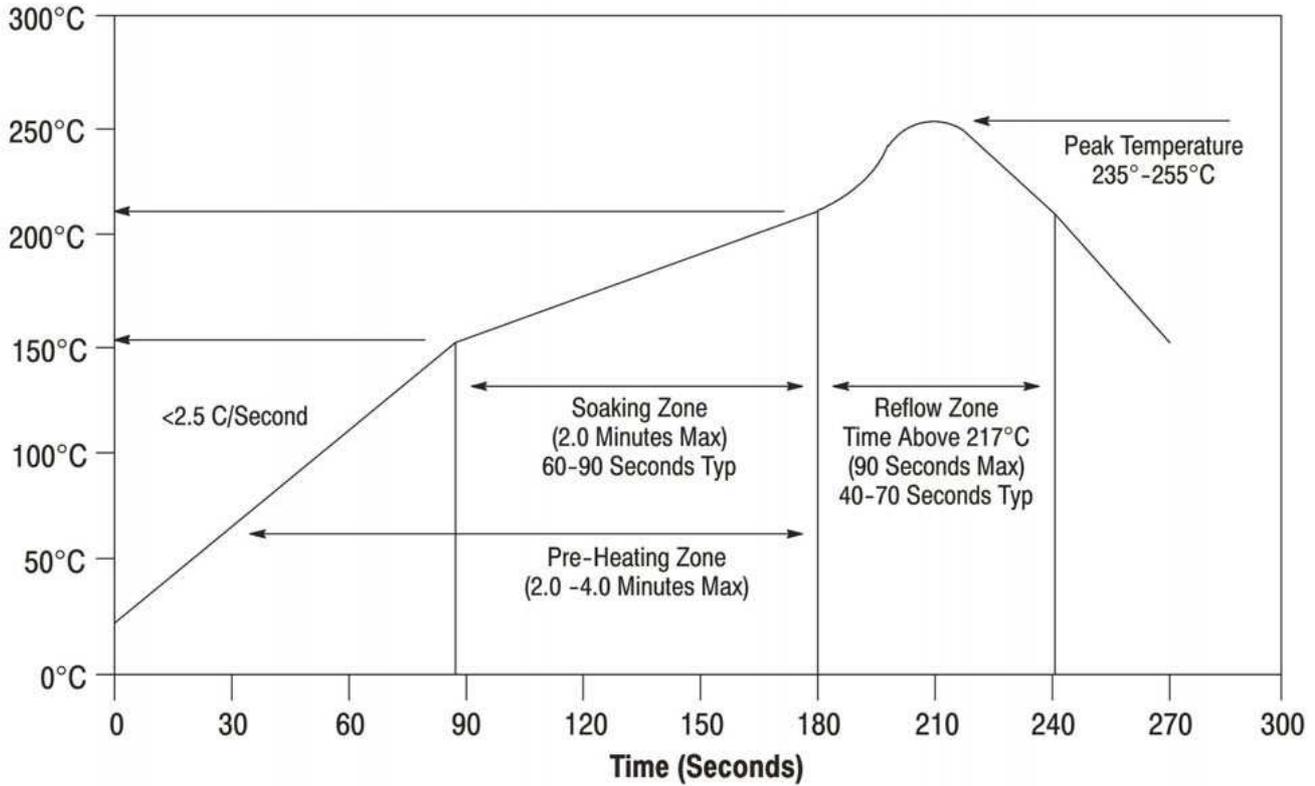


Figure 4

6. VISUAL AID

The illustration below shows a typical application of this Connector. This illustration should be used by production personnel to ensure a correctly applied product. Applications which **DO NOT** appear correct, should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product.

